

**High fluidity**  
**Excellent fillability for narrow gap/pitch**  
**Reduced void/bleed**

**Applications**  
**IC Package/Mobile**  
 High-density advanced IC packages (BGA, CSP)

## LEXCM<sup>DF</sup>

# CV5300 series

**Capillary underfill (CUF) semiconductor encapsulation materials**

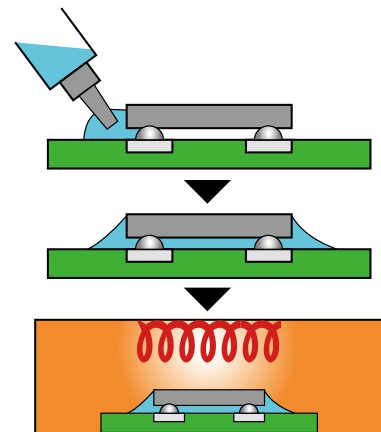
High capillary flow rate fills narrow gaps without voiding.

### Line-up

#### Features

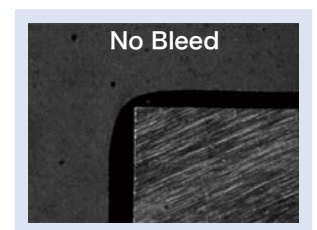
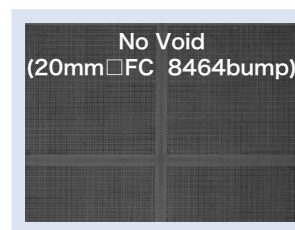
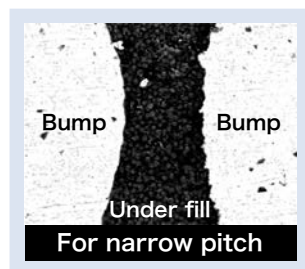
- 1 Compatible with narrow gap
- 2 Uniform penetration
- 3 High-speed fillability
- 4 Compatible with low-k film
- 5 High moisture reflow resistance

Part Number	Features
CV5300 series	High fluidity, Short-time curing



### Excellent fillability for narrow gap/pitch

### Reduced void/bleed



### General properties

Item	Unit	CV5300 series
Filler size Max	μm	1
C.T.E.	ppm/°C	33
Tg (TMA)	°C	110
Modulus	GPa	7

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

[industrial.panasonic.com/ww/electronic-materials](http://industrial.panasonic.com/ww/electronic-materials)

Panasonic Industry Co., Ltd. Electronic Materials Business Division

Panasonic Industry CV5300

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